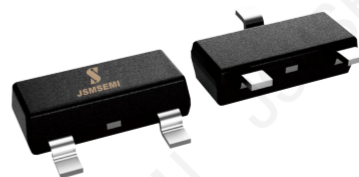
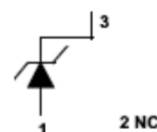


## FEATURES

- ◆ Planar Die Construction.
- ◆ 350mw Power Dissipation.
- ◆ Zener Voltages From 2.4V -51V
- ◆ Ideally Suited For Automated Assembly Processes



**CONNECTION  
DIAGRAM**



## APPLICATIONS

- ◆ 350Mw Surface mount zener diode

## MAXIMUM RATING @ Ta=25°C unless otherwise specified

| Characteristic                              | Symbol                            | Value      | Unit |
|---------------------------------------------|-----------------------------------|------------|------|
| Forward Voltage@I <sub>F</sub> =10mA        | V <sub>F</sub>                    | 0.9        | V    |
| Power Dissipation                           | P <sub>d</sub>                    | 350        | mW   |
| Thermal Resistance, Junction to Ambient Air | R <sub>θJA</sub>                  | 357        | °C/W |
| Operating and Storage Temperature Range     | T <sub>J</sub> , T <sub>stg</sub> | -65 to+150 | °C   |

Notes: 1. Valid provided that device terminals are kept at ambient temperature.

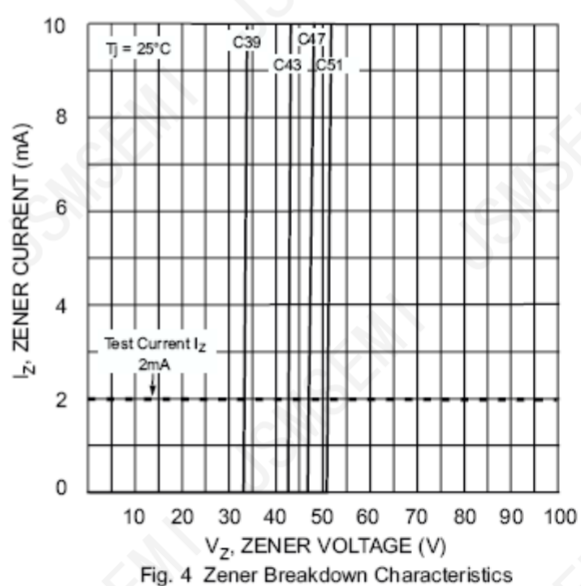
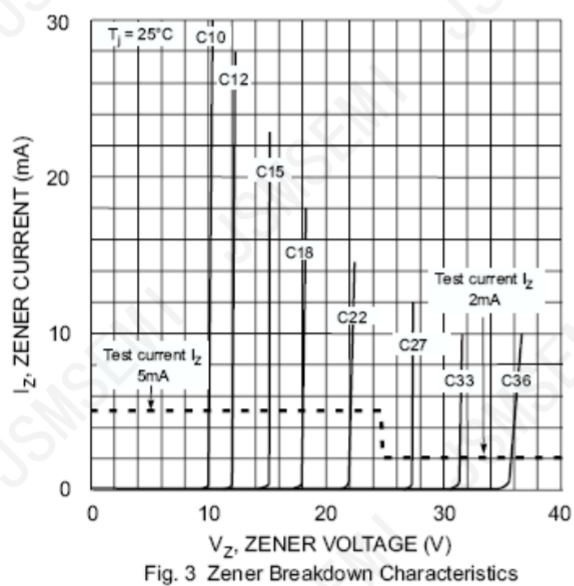
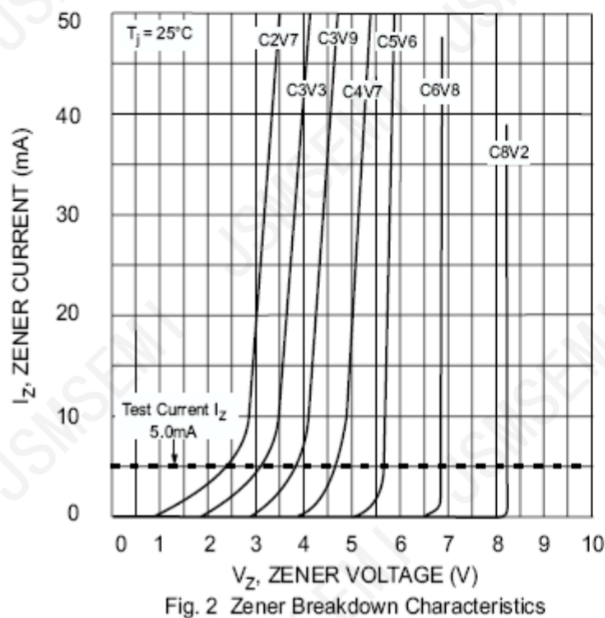
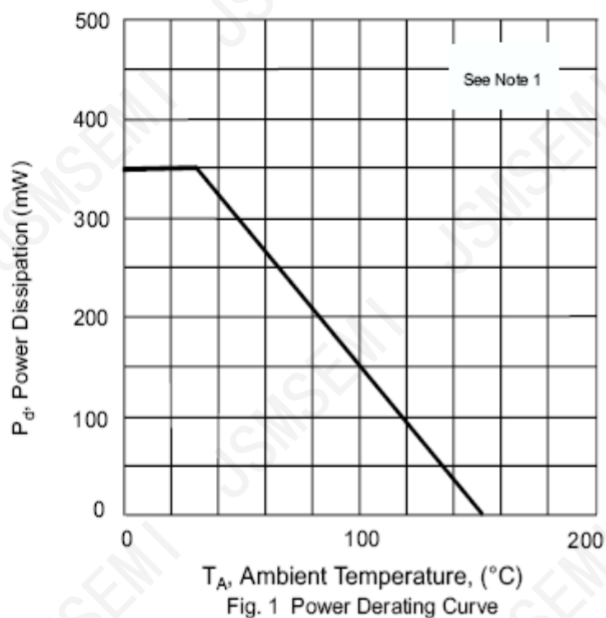
2. Tested with pulses, 300μs pulse width, period = 5ms.

3. f = 1KHz.

## ELECTRICAL CHARACTERISTICS@ Ta=25°C unless otherwise specified

| Type<br>Number         | Marking<br>Code | Zener Voltage Range             |        |        |                 | Maximum Zener<br>Impedance       |                                  |      | Maximum<br>Reverse<br>Current |                | Typical<br>Temperature<br>Coefficient @I <sub>ZT</sub><br>mV/°C |     |
|------------------------|-----------------|---------------------------------|--------|--------|-----------------|----------------------------------|----------------------------------|------|-------------------------------|----------------|-----------------------------------------------------------------|-----|
|                        |                 | V <sub>Z</sub> @I <sub>ZT</sub> |        |        | I <sub>ZT</sub> | Z <sub>ZT</sub> @I <sub>ZT</sub> | Z <sub>ZK</sub> @I <sub>ZK</sub> |      | I <sub>R</sub>                | V <sub>R</sub> | Min                                                             | Max |
|                        |                 | Nom(V)                          | Min(V) | Max(V) | (mA)            | (Ω)                              | (Ω)                              | (mA) | (μA)                          | (V)            |                                                                 |     |
| BZX84-<br>C3V3,215-JSM | Z14             | 3.3                             | 3.1    | 3.5    | 5.0             | 95                               | 600                              | 1.0  | 5.0                           | 1.0            | -3.5                                                            | 0   |

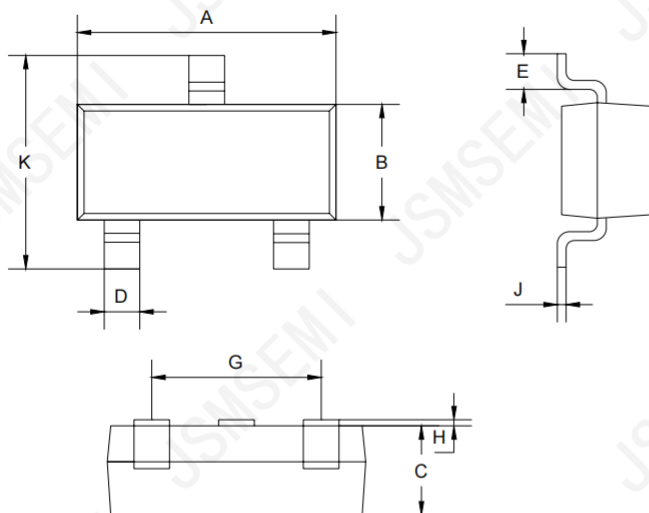
TYPICAL CHARACTERISTICS @  $T_a=25^\circ\text{C}$  unless otherwise specified



## PACKAGE OUTLINE

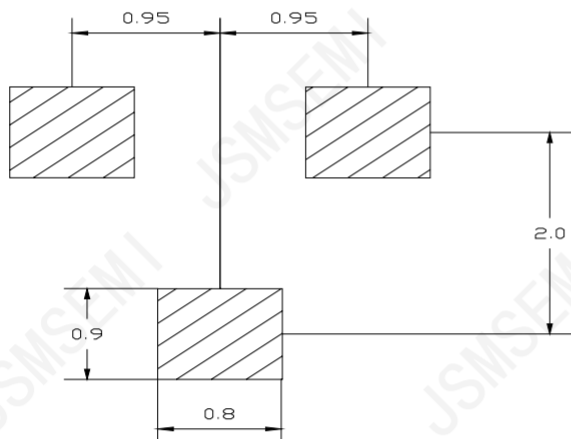
Plastic surface mounted package

SOT-23



| SOT-23               |            |      |
|----------------------|------------|------|
| Dim                  | Min        | Max  |
| A                    | 2.85       | 2.95 |
| B                    | 1.25       | 1.35 |
| C                    | 1.0Typical |      |
| D                    | 0.37       | 0.43 |
| E                    | 0.35       | 0.48 |
| G                    | 1.85       | 1.95 |
| H                    | 0.02       | 0.1  |
| J                    | 0.1Typical |      |
| K                    | 2.35       | 2.45 |
| All Dimensions in mm |            |      |

## SOLDERING FOOTPRINT



Unit : mm

## PACKAGE INFORMATION

| Device             | Package | Shipping       |
|--------------------|---------|----------------|
| BZX84-C3V3,215-JSM | SOT-23  | 3000/Tape&Reel |

## Revision History

| Rev. | Change          | Date      |
|------|-----------------|-----------|
| V1.0 | Initial version | 2/23/2024 |
|      |                 |           |

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